



Material Content Data Sheet



Sales Product Name		TLE4965-5M		Issued		2. August 2018		
MA#		MA001318118						
Package		PG-SOT23-3-15		Weight*		9.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.220	2.25	2.25	22463	22463
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		74	
	non noble metal	titanium	7440-32-6	0.004	0.04		369	
	non noble metal	chromium	7440-47-3	0.011	0.11		1106	
wire	non noble metal	copper	7440-50-8	3.590	36.72	36.88	367217	368766
	noble metal	gold	7440-57-5	0.023	0.24	0.24	2361	2361
	encapsulation	organic material	carbon black	1333-86-4	0.055	0.56		5619
encapsulation	plastics	epoxy resin	-	1.181	12.08		120813	
	inorganic material	silicondioxide	60676-86-0	4.257	43.55	56.19	435487	561919
leadfinish	non noble metal	tin	7440-31-5	0.150	1.53	1.53	15308	15308
plating	noble metal	silver	7440-22-4	0.149	1.52	1.52	15200	15200
glue	plastics	epoxy resin	-	0.024	0.24		2447	
	noble metal	silver	7440-22-4	0.113	1.15	1.39	11536	13983
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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